

**PS2566-1,-2, PS2566L-1,-2****HIGH ISOLATION VOLTAGE  
AC INPUT, DARLINGTON TRANSISTOR TYPE  
MULTI PHOTOCOUPLER SERIES****DESCRIPTION**

The PS2566-1, -2 and PS2566L-1, -2 are optically coupled isolators containing GaAs light emitting diodes and an NPN silicon darlington connected phototransistor.

PS2566-1, -2 are in a plastic DIP (Dual In-line Package) and PS2566L-1, -2 are lead bending type (Gull-wing) for surface mount.

**FEATURES**

- AC input response
- High isolation voltage      BV = 5 000 Vr.m.s.: standard products  
   BV = 3 750 Vr.m.s.: VDE0884 approved products (Option)
- High current transfer ratio (CTR = 2 000 % TYP.)
- High-speed switching ( $t_r$ ,  $t_f$  = 100  $\mu$ s TYP.)
- UL approved (File No. E72422 (S) )
- ★ • CSA approved (No. CA 101391)
- BSI approved (BS415, BS7002) No. 7112
- SEMKO approved (SS4410165) No. 9317144
- NEMKO approved (NEK-HD 195S6) No. A21409
- DEMKO approved (Section 101, 137) No. 300535
- ★ • FIMKO approved (E69-89) No. 167265-08
- VDE0884 approved (Option)

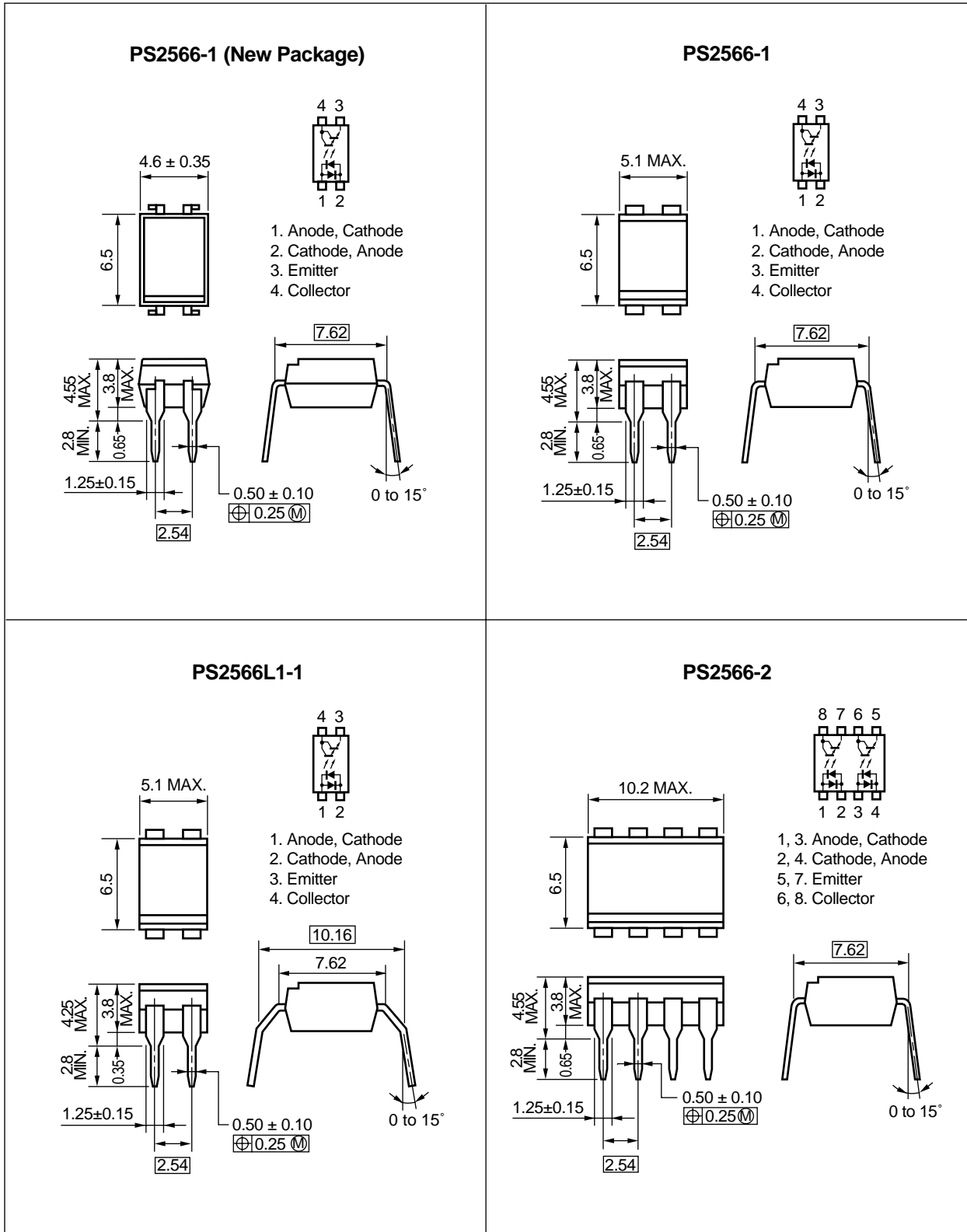
**APPLICATIONS**

- Telephone/FAX.
- FA/OA equipment
- Programmable logic controller

The information in this document is subject to change without notice.

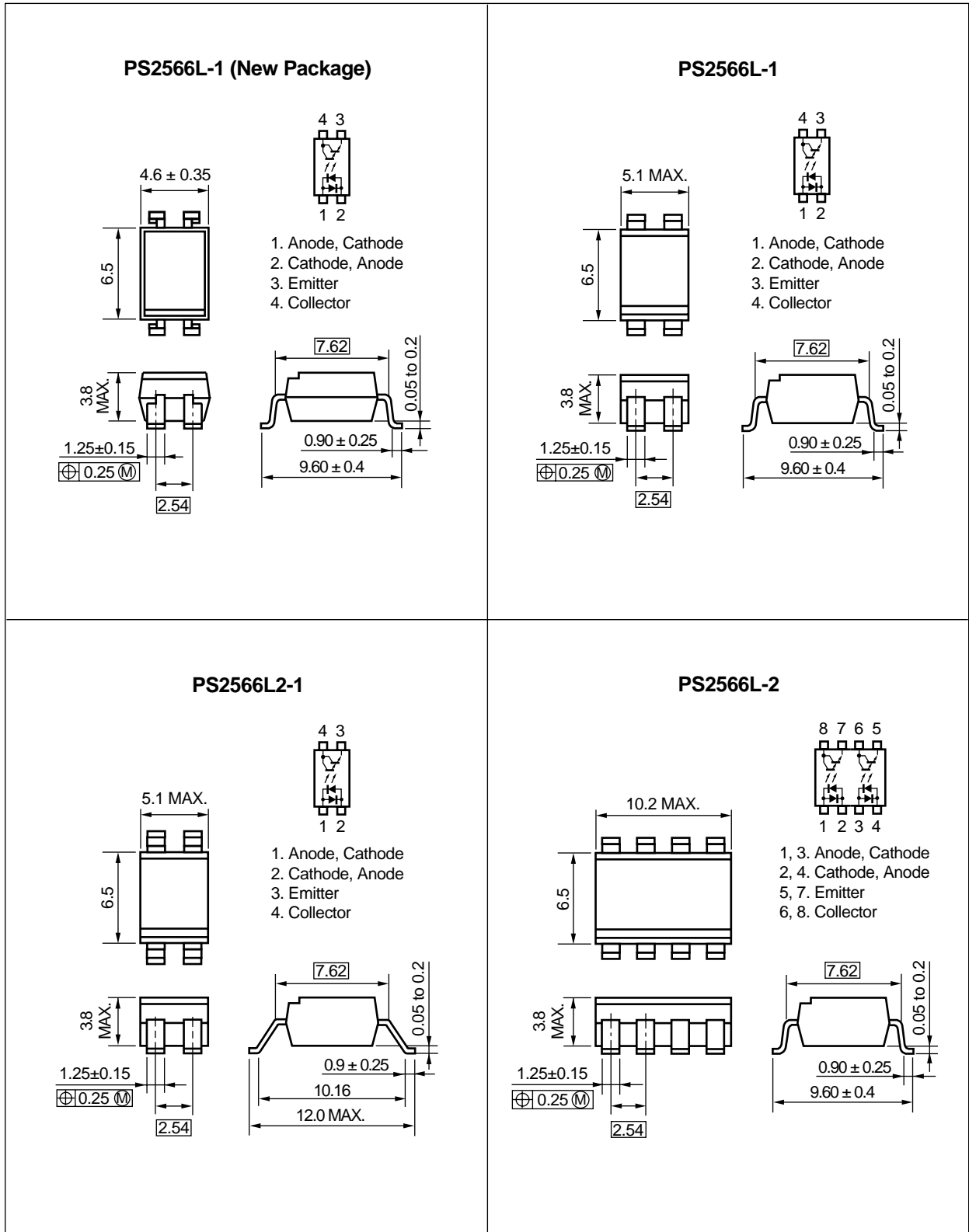
★ PACKAGE DIMENSIONS (in millimeters)

DIP Type



Caution New package 1ch only

Lead Bending Type



Caution New package 1ch only

★ ORDERING INFORMATION

Part Number	Package	Safety Standard Approval	Application part number <sup>*1</sup>
PS2566-1 PS2566L-1 PS2566L1-1 PS2566L2-1	4-pin DIP 4-pin DIP (lead bending surface mount) 4-pin DIP (for long distance) 4-pin DIP (for long distance surface mount)	Standard products • UL approved      • CSA approved • BSI approved      • NEMKO approved • DEMKO approved   • SEMKO approved • FIMKO approved	PS2566-1
PS2566-2 PS2566L-2	8-pin DIP 8-pin DIP (lead bending surface mount)		PS2566-2
PS2566-1-V PS2566L-1-V PS2566L1-1-V PS2566L2-1-V	4-pin DIP 4-pin DIP (lead bending surface mount) 4-pin DIP (for long distance) 4-pin DIP (for long distance surface mount)	VDE0884 approved products (Option)	PS2566-1
PS2566-2-V PS2566L-2-V	8-pin DIP 8-pin DIP (lead bending surface mount)		PS2566-2

\*1 As applying to Safety Standard, following part number should be used.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise specified)**

Parameter	Symbol	Ratings		Unit	
		PS2566-1, PS2566L-1	PS2566-2, PS2566L-2		
★ Diode	Forward Current (DC)	I <sub>F</sub>	80		mA
	Power Dissipation Derating	ΔP <sub>D</sub> /°C	1.5	1.2	mW/°C
	Power Dissipation	P <sub>D</sub>	150	120	mW/ch
	Peak Forward Current <sup>*1</sup>	I <sub>FP</sub>	1		A
★ Transistor	Collector to Emitter Voltage	V <sub>CEO</sub>	40		V
	Emitter to Collector Voltage	V <sub>ECO</sub>	6		V
	Collector Current	I <sub>C</sub>	200	160	mA/ch
	Power Dissipation Derating	ΔP <sub>C</sub> /°C	2.0	1.6	mW/°C
	Power Dissipation	P <sub>C</sub>	200	160	mW/ch
Isolation Voltage <sup>*2</sup>	BV	5 000 3 750 <sup>*3</sup>		Vr.m.s.	
Operating Ambient Temperature	T <sub>A</sub>	-55 to +100		°C	
Storage Temperature	T <sub>stg</sub>	-55 to +150		°C	

\*1 PW = 100 μs, Duty Cycle = 1 %

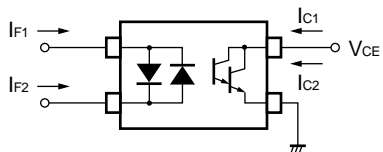
\*2 AC voltage for 1 minute at T<sub>A</sub> = 25 °C, RH = 60 % between input and output

\*3 VDE0884 approved products (Option)

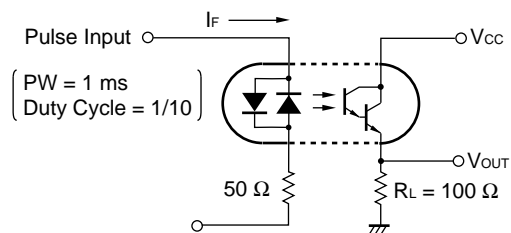
ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
★ Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = ±10 mA		1.17	1.4	V
	Terminal Capacitance	C <sub>t</sub>	V = 0 V, f = 1.0 MHz		100		pF
Transistor	Collector to Emitter Dark Current	I <sub>CEO</sub>	V <sub>CE</sub> = 40 V, I <sub>F</sub> = 0 mA			400	nA
Coupled	Current Transfer Ratio	CTR	I <sub>F</sub> = ±1 mA, V <sub>CE</sub> = 2 V	200	2 000		%
	CTR Ratio <sup>*1</sup>	CTR <sub>1</sub> /CTR <sub>2</sub>	I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 2 V	0.3	1.0	3.0	
	Collector Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>F</sub> = ±1 mA, I <sub>c</sub> = 2 mA			1.0	V
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1.0 kV	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1.0 MHz		0.5		pF
	Rise Time <sup>*2</sup>	t <sub>r</sub>	V <sub>CC</sub> = 10 V, I <sub>c</sub> = 10 mA, R <sub>L</sub> = 100 Ω		100		μs
Fall Time <sup>*2</sup>	t <sub>f</sub>			100			

\*1 CTR<sub>1</sub> = I<sub>c1</sub>/I<sub>F1</sub>, CTR<sub>2</sub> = I<sub>c2</sub>/I<sub>F2</sub>

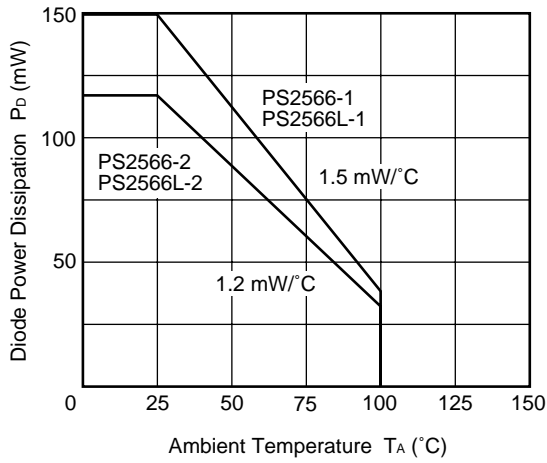


\*2 Test circuit for switching time

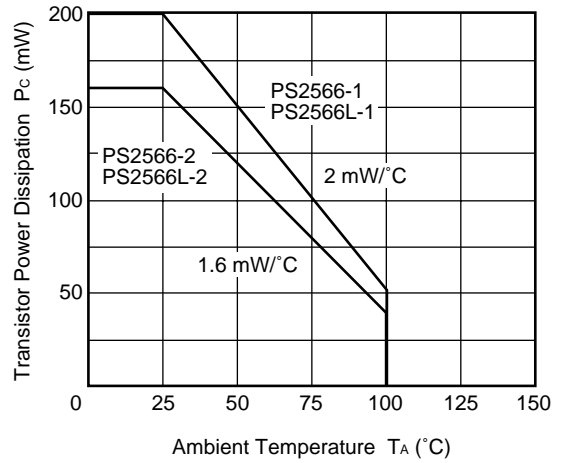


★ TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise specified)

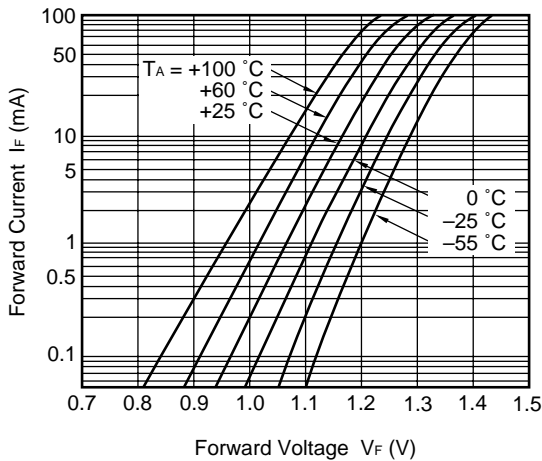
DIODE POWER DISSIPATION vs. AMBIENT TEMPERATURE



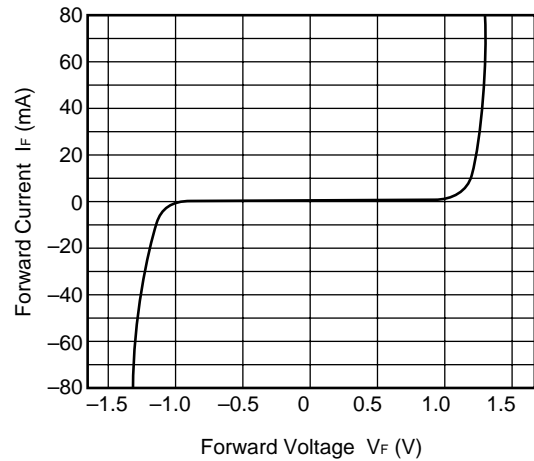
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



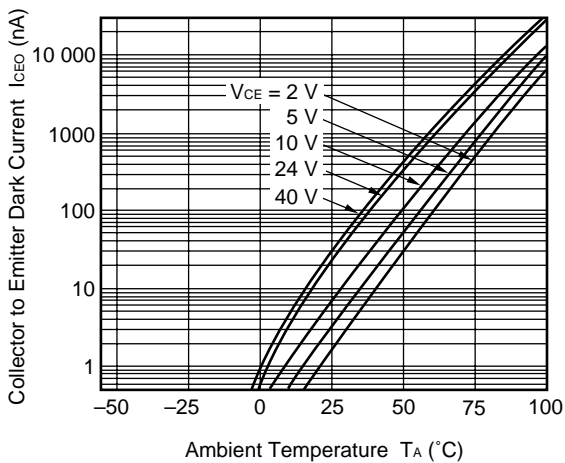
FORWARD CURRENT vs. FORWARD VOLTAGE



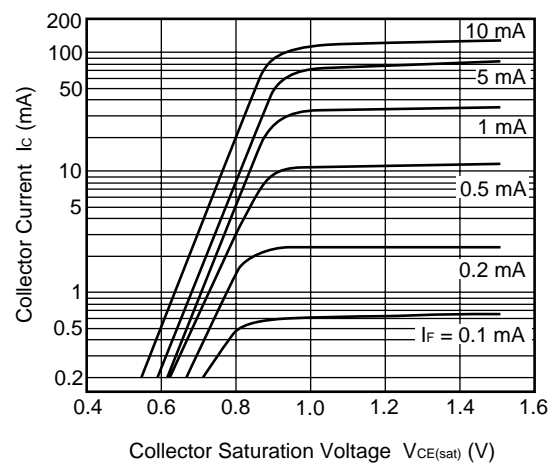
FORWARD CURRENT vs. FORWARD VOLTAGE



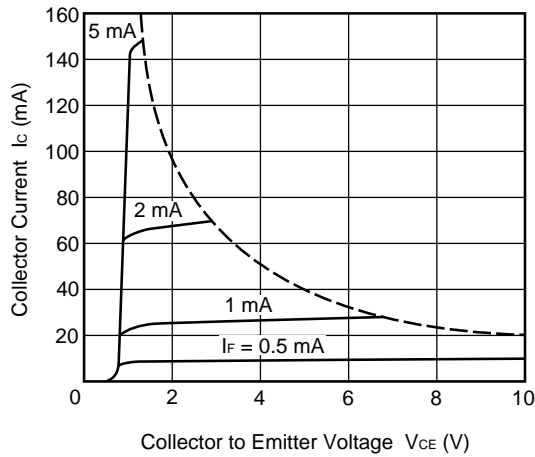
COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE



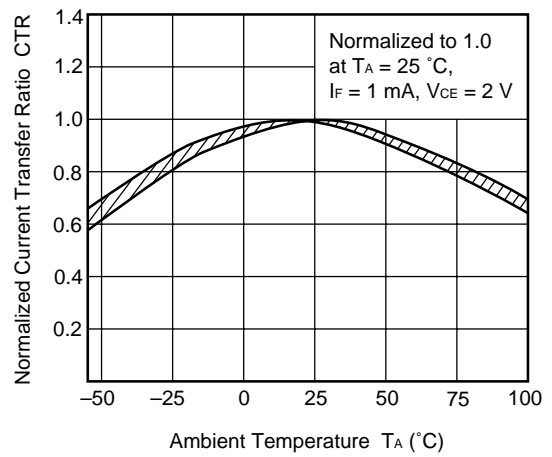
COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE



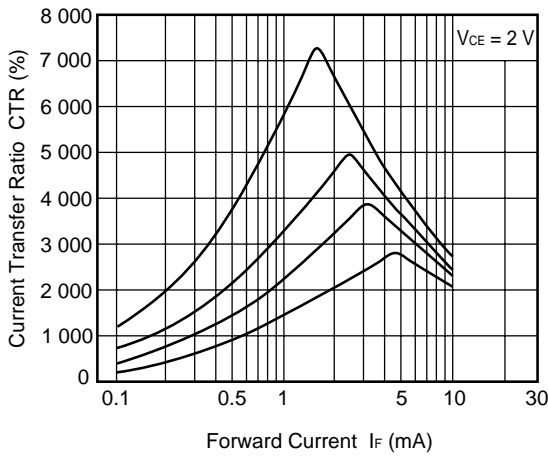
COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE



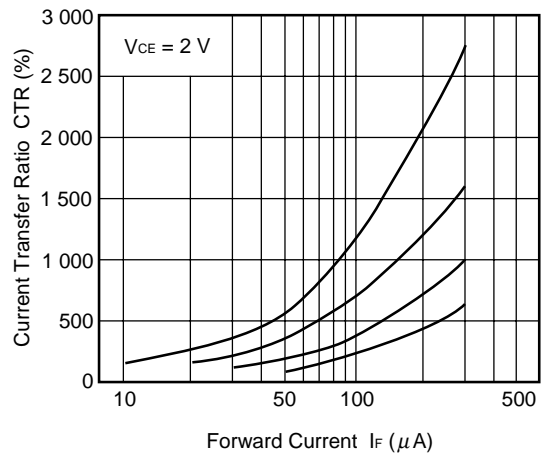
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



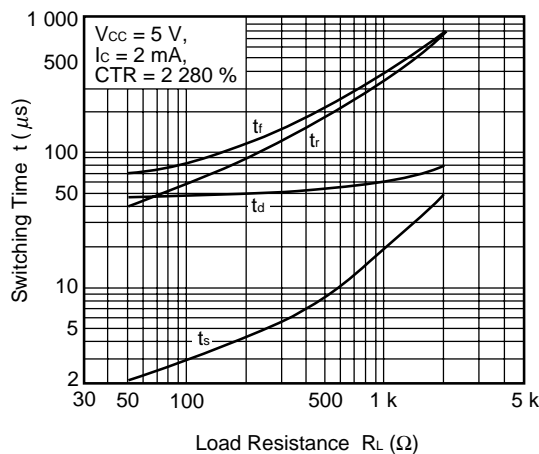
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



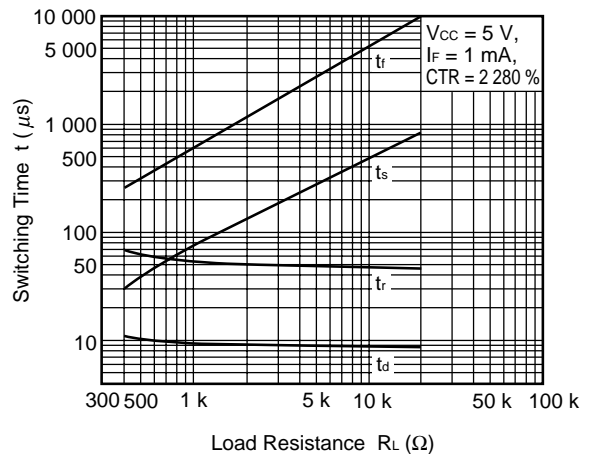
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



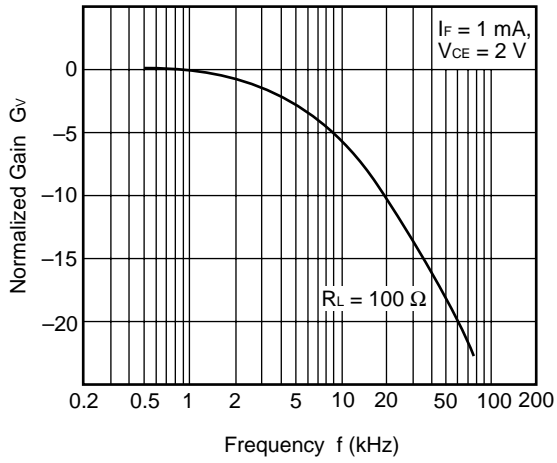
SWITCHING TIME vs. LOAD RESISTANCE



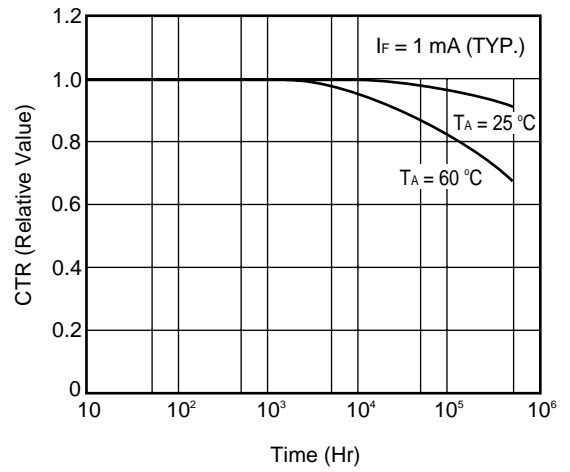
SWITCHING TIME vs. LOAD RESISTANCE



FREQUENCY RESPONSE



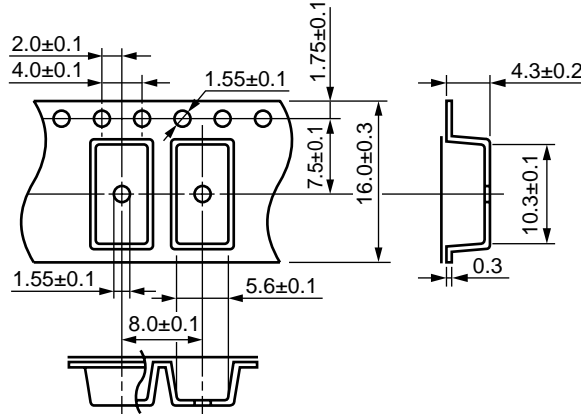
LONG TIME CTR DEGRADATION



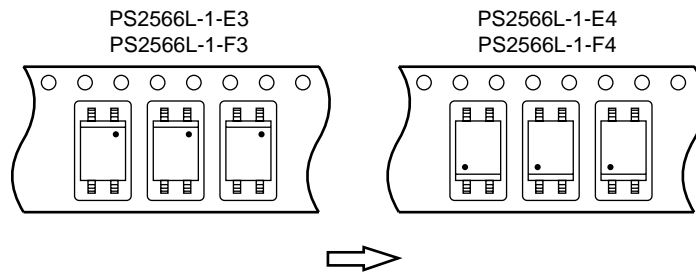


★ TAPING SPECIFICATIONS (in millimeters)

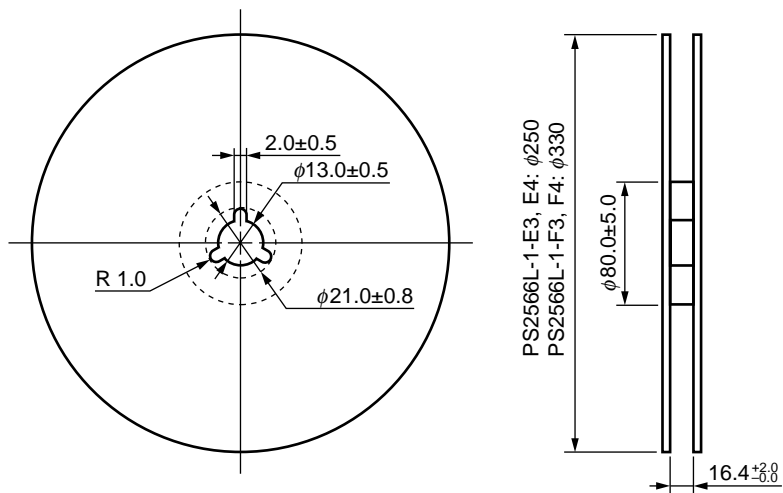
Outline and Dimensions (Tape)



Taping Direction

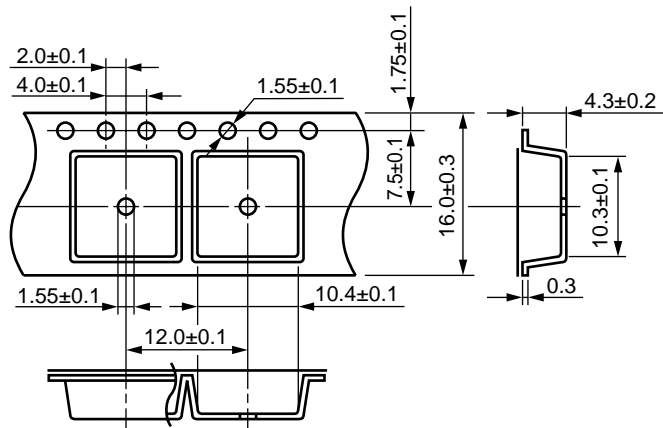


Outline and Dimensions (Reel)

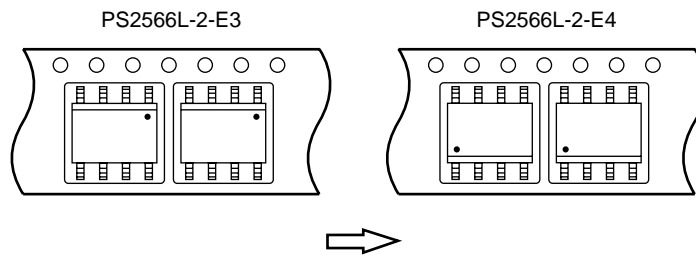


Packing: PS2566L-1-E3, E4 1 000 pcs/reel  
 PS2566L-1-F3, F4 2 000 pcs/reel

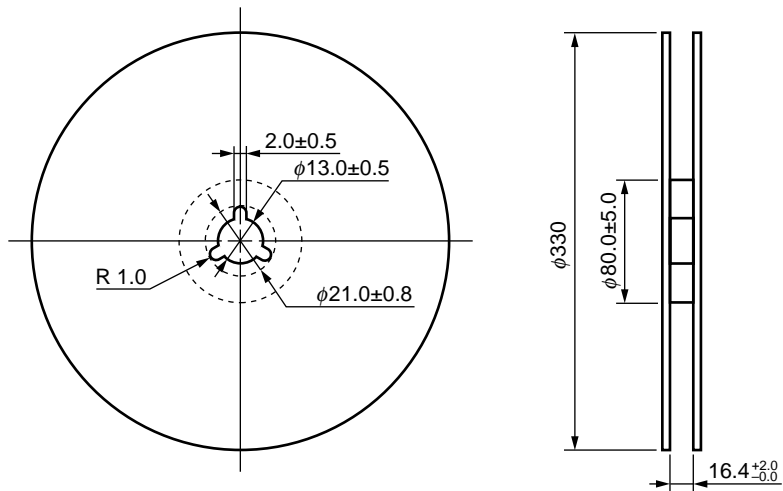
Outline and Dimensions (Tape)



Taping Direction



Outline and Dimensions (Reel)



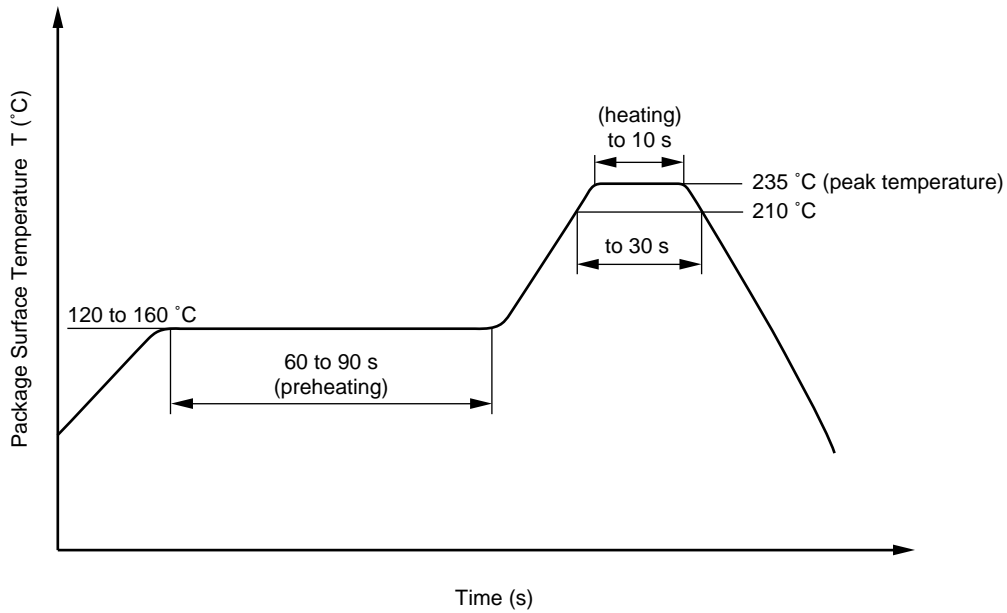
Packing: 1 000 pcs/reel

★ **RECOMMENDED SOLDERING CONDITIONS**

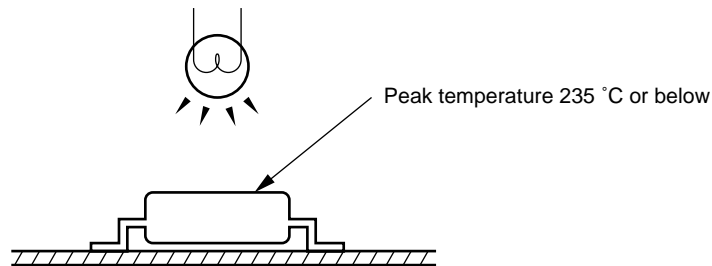
**(1) Infrared reflow soldering**

- Peak reflow temperature 235 °C (package surface temperature)
- Time of temperature higher than 210 °C 30 seconds or less
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

Recommended Temperature Profile of Infrared Reflow



**Caution** Please avoid to removed the residual flux by water after the first reflow processes.



**(2) Dip soldering**

- Temperature 260 °C or below (molten solder temperature)
- Time 10 seconds or less
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

**SPECIFICATION OF VDE MARKS LICENSE DOCUMENT (VDE0884)**

Parameter	Symbol	Speck	Unit
Application classification (DIN VDE 0109) for rated line voltages $\leq 300$ Vr.m.s. for rated line voltages $\leq 600$ Vr.m.s.		IV III	
Climatic test class (DIN IEC 68 Teil 1/09.80)		55/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test procedure a for type test and random test) $U_{pr} = 1.2 \times U_{IORM}$ , $P_d < 5$ pC	$U_{IORM}$ $U_{pr}$	890 1 068	$V_{peak}$ $V_{peak}$
Test voltage (partial discharge test procedure b for random test) $U_{pr} = 1.6 \times U_{IORM}$ , $P_d < 5$ pC	$U_{pr}$	1 424	$V_{peak}$
Highest permissible overvoltage	$U_{TR}$	6 000	$V_{peak}$
Degree of pollution (DIN VDE 0109)		2	
Clearance distance		$> 7.0$	mm
Creepage distance		$> 7.0$	mm
Comparative tracking index (DIN IEC 112/VDE 0303 part 1)	CTI	175	
Material group (DIN VDE 0109)		III a	
Storage temperature range	$T_{stg}$	-55 to +150	$^{\circ}C$
Operating temperature range	$T_A$	-55 to +100	$^{\circ}C$
Isolation resistance, minimum value $V_{IO} = 500$ V dc at $T_A = 25$ $^{\circ}C$ $V_{IO} = 500$ V dc at $T_A$ MAX. at least 100 $^{\circ}C$	Ris MIN. Ris MIN.	$10^{12}$ $10^{11}$	$\Omega$ $\Omega$
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current $I_F$ , $\Psi_i = 0$ ) Power (output or total power dissipation) Isolation resistance $V_{IO} = 500$ V dc at $T_A = 175$ $^{\circ}C$ ( $T_{si}$ )	$T_{si}$ $I_{si}$ $\Psi_{si}$ Ris MIN.	175 400 700 $10^9$	$^{\circ}C$ mA mW $\Omega$

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**CAUTION**

**Within this device there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstances break the hermetic seal.**

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Anti-radioactive design is not implemented in this product.